

INFORMATION DISCLOSURE CITATION	Applicant: Takemi MUROGA et al Ser. No.: Unknown Filed: Unknown Conf. No.: Unknown Atty. Ref.: Komatsu Case 291 Group: Unknown
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U.S. PATENT DOCUMENTS							
Examiner Initial*	Document Number	Date	Name	Class	Sub Class	Filing Date	
	AA						
	AB						
	AC						

FOREIGN PATENT DOCUMENTS					
	Document Number	Date	Country	Class	Sub Class
CC	AD JP 11-86647	3/1999	Japan	English abstract attached	
CC	AE JP 2721595	11/1997	Japan	English abstract attached	
	AF				
	AG				
	AH				

OTHER DOCUMENTS (Including Author, Title, Date, Pages, Etc.)

CC	AI	M.W. Rupich, et al, "Low Cost Y-Ba-Cu-O Coated Conductors", IEEE TRANSACTIONS ON APPLIED SUPERCONDUCTIVITY, Vol. 11, No. 1 (March 2001), p. 2927-2930
	AJ	Q.X. Jia, et al, "Superconducting YBCO films on polycrystalline yttrium-iron-garnet using IBAD-YSZ as a template", IEEE TRANSACTIONS ON APPLIED SUPERCONDUCTIVITY, Vol. 11, No. 1 (March 2001), p. 3489-3492
	AK	Terry G. Holesinger, et al, "A Comparison of Buffer Layer Architectures on Continuously Processed YBCO Coated Conductors Based on the IBAD YSZ Process", IEEE TRANSACTIONS ON APPLIED SUPERCONDUCTIVITY, Vol. 11, No. 1 (March 2001), p. 3359-3364
	AL	T.G. Holesinger, et al, "The microstructure of continuously processed $\text{YBa}_2\text{Cu}_3\text{O}_y$ coated conductors with underlying $\text{CeO}_2$ and ion-beam-assisted yttria-stabilized zirconia buffer layers", J. MATER. RES., Vol. 15, No. 5 (May 2000), p. 1110-1119
CC	AM	Y. Takahashi, et al, "Preparation of YBCO films on $\text{CeO}_2$ buffered metallic substrates by the TFA-MOD method", PHYSICA C 357-360 (2001), p. 1003-1006

*Colleen L. Conk* DATE CONSIDERED 6/24/05

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.